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Atty. Docket No. CPAC 1017-2
Appl. No. 10/632,549

AUG 03 2004
OFFICIAL

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos

Application No.: 10/632,549

Filed: August 2, 2003

Title: **Semiconductor multi-package module having
wire bond interconnect between stacked
packages**

) Examiner: Phat X. CAO


) Group Art Unit: 2569

) Date: August 3, 2004

) **CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being facsimile transmitted to the
United States Patent and Trademark Office, at the
Central Fax No. 703 872-9306 on August 3, 2004.

Signed


Paula Faulk Hurley

RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

Responsive to the Office action mailed July 22, 2004 (Restriction only), Applicants elect:
Group I, claims 1 - 10.

Amendments to the Specification begin on page 2 of this paper.

There are no amendments to the claims. A **Listing of Claims** is included for the
Examiner's convenience, beginning on page 3 of this paper.

Remarks begin on page 5 of this paper.